

(19) World Intellectual Property Organization
International Bureau



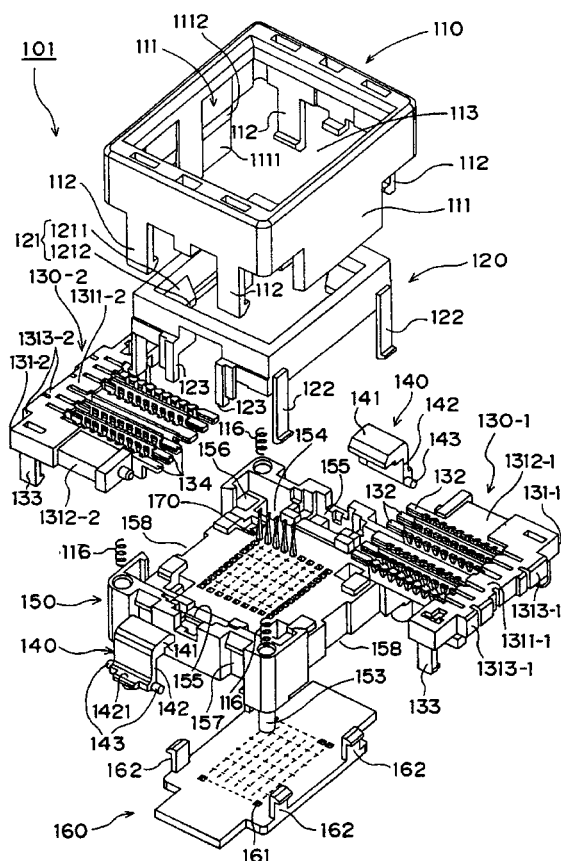
(43) International Publication Date
23 August 2001 (23.08.2001)

PCT

(10) International Publication Number
WO 01/61364 A3

- (51) International Patent Classification⁷: **G01R 1/04**
- (74) Agents: **FONSECA, Darla, P.** et al.; Office of Intellectual Property Counsel, P.O. Box 33427, Saint Paul, MN 55133-3427 (US).
- (21) International Application Number: PCT/US01/04567
- (22) International Filing Date: 13 February 2001 (13.02.2001)
- (81) Designated States (*national*): KR, SG.
- (25) Filing Language: English
- (84) Designated States (*regional*): European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR).
- (26) Publication Language: English
- (30) Priority Data:
2000-34990 14 February 2000 (14.02.2000) JP
- Published:**
— with international search report
- (71) Applicant: **3M INNOVATIVE PROPERTIES COMPANY** [US/US]; 3M Center, P.O. Box 33427, Saint Paul, MN 55133-3427 (US).
- (88) Date of publication of the international search report:
7 March 2002
- (72) Inventors: **NAITO, Masahito**; 4-12-21-202, Kyowa, Sagami-hara-city, Kanagawa 229-0034 (JP). **NAGUMO, Takayuki**; 9-28, Hishimoto 4-chome, Sagami-hara-city, Kanagawa 229-1103 (JP).
- For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.*

(54) Title: SEMICONDUCTOR COMPONENT TEST SOCKET



(57) Abstract: A semiconductor component test socket may be used to connect semiconductor components to a semiconductor component testing apparatus. The test socket is small, light in weight, and has a lower manufacturing cost than conventional test sockets. The test socket includes an interposing assembly and a frame body that includes a biasing member for moving interposed first and second interposing members, of the interposing assembly, from a standby position to a compact position for releasably connecting a semiconductor component to the semiconductor component test socket.